

Ceramic Plate Series Thermoelectric Cooler

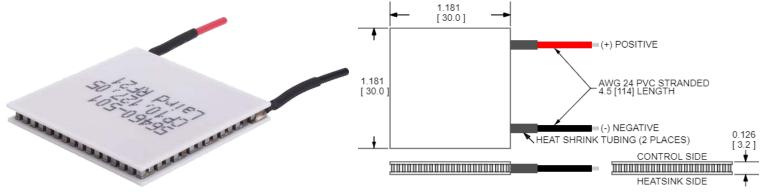
The CP10-127-05-L2-W4.5 is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Qc of 33 Watts when $\Delta T=0$ and a maximum ΔT of 70.5 °C at Qc = 0.

Features

- Compact geometric sizes
- DC Operation
- RoHS-compliant

Applications

- Thermoelectric Coolers for Reagent Storage
- Thermoelectric Coolers for Handheld Cosmetic Lasers
- Cooling for Centrifuges
- Heads-Up Displays, Imaging Sensors
- Peltier Cooling for Machine Vision

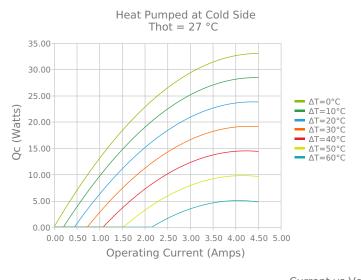


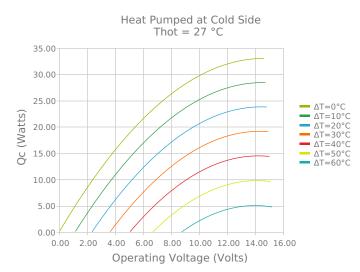
CERAMIC MATERIAL: Al₂O₃ SOLDER CONSTRUCTION: 138°C, BiSn

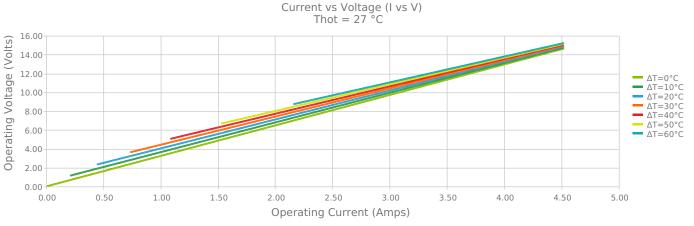
INCHES [MM]

ELECTRICAL AND THERMAL PERFORMANCE

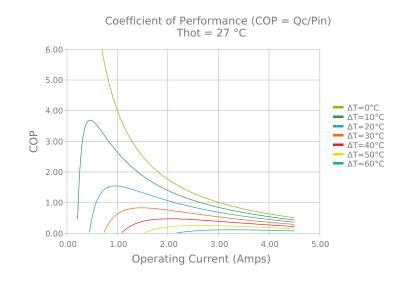
For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the HEATSINK side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

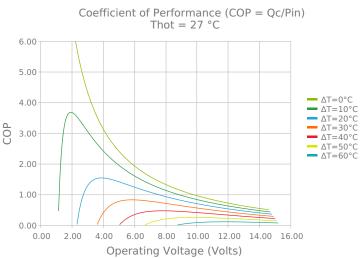


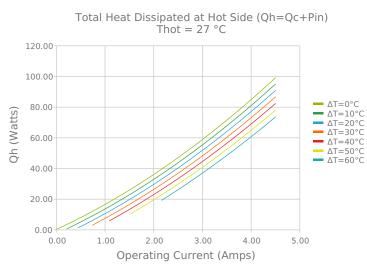


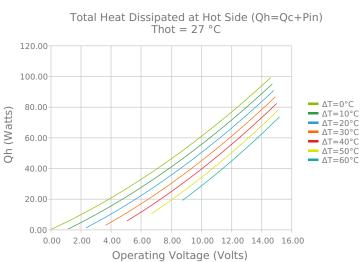


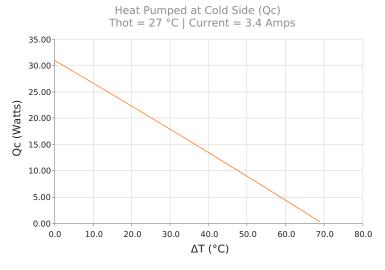


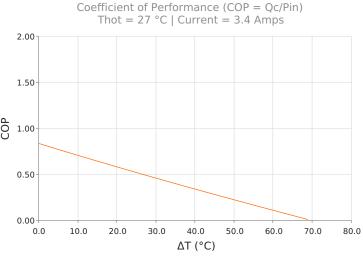














SPECIFICATIONS*

Hot Side Temperature

 $Qcmax (\Delta T = 0)$

 $\Delta T max (Qc = 0)$

Imax (I @ \Darkstrum \

Vmax (V @ Δ Tmax)

Module Resistance

Max Operating Temperature

Weight

27.0 °C	35.0 °C	50.0 °C
33.0 Watts	34.0 Watts	35.8 Watts
70.5°C	73.5°C	78.8°C
4.0 Amps	4.0 Amps	3.9 Amps
13.9 Volts	14.4 Volts	15.4 Volts
3.24 Ohms	3.37 Ohms	3.62 Ohms
80 °C		
9.0 gram(s)		

FINISHING OPTIONS

Suffix		Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length	
	L2	3.200 ±0.013 mm 0.126 ± 0.0005 in	0.013 mm / 0.013 mm 0.0005 in / 0.0005 in	Lapped	Lapped	114.3 mm 4.50 in	

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
	None			No sealing specified

NOTES

- 1. Max operating temperature: 80°C
- 2. Do not exceed Imax or Vmax when operating module
- 3. Reference assembly guidelines for recommended installation
- 4. Solder tinning also available on metallized ceramics

Any information furnished by Laird and its agents, whether in specifications, data sheets, product catalogues or otherwise, is believed to be (but is not warranted as being) accurate and reliable, is provided for information only and does not form part of any contract with Laird. All specifications are subject to change without notice. Laird assumes no responsibility and disclaims all liability for losses or damages resulting from use of or reliance on this information. All Laird products are sold subject to the Laird Terms and Conditions of sale (including Laird's limited warranty) in effect from time to time, a copy of which will be furnished upon request.

© Copyright 2019-2022 Laird Thermal Systems, Inc. All rights reserved. Laird $^{™}$, the Laird Ring Logo, and Laird Thermal Systems $^{™}$ are trademarks or registered trademarks of Laird Limited or its subsidiaries.

Revision: 00 Date: 06-01-2022

Print Date: 06-09-2022

^{*} Specifications reflect thermoelectric coefficients updated March 2020